



Removing charges during peel-off of BG sheet

OUTLINE / PREVIOUS

Customer: Semiconductor equipment manufacturer

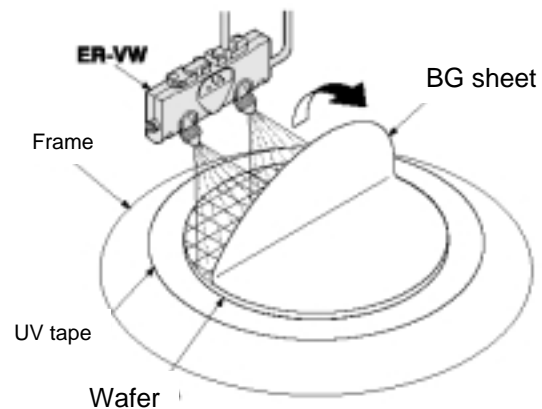
Process: Back Grinding process

After front-end process, rear surface of wafer is grinded to thin. Charges around wafer are removed during peel-off of BG sheet.

PROBLEM

Static remover is to be installed close to wafer.

SOLUTION



MODEL / HOW TO

ER-VW

Mount **ER-VW** vertically and adjust nozzle angle.

BENEFIT 1 Compact and thin design

ER-VW is designed as W127 x H18.9 x D64.3 mm, compact and thin. The nozzle angles can be adjusted so that **ER-VW** can be installed in places where there are space restrictions, such as internal space of equipment, or when installing in several adjacent lines.

BENEFIT 2 Nozzle angle adjustment mechanism

ER-VW has two nozzles which tips are screwed to adjust angles within a range of approx. 190 degrees. This allows nozzle angle adjustment to be easy after installation of **ER-VW**.

BENEFIT 3 Air supply monitoring function

This function stops discharging automatically when the supply of air drops below a certain pressure. Notifies by lighting up of the indicator (AIR) and lighting off of the discharge output (DSC). This avoids to leave out charge removal of objects when air supply is stopped.

